Product Preview **Silicon Carbide Schottky Diode, 650 V, 20 A**

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 49 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- AEC-Q101 Qualified
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Applications

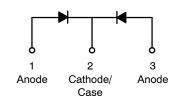
- Automotive HEV–EV Onboard Chargers
- Automotive HEV-EV DC-DC Converters

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

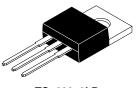


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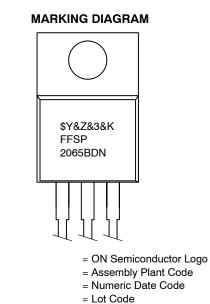
www.onsemi.com



Schottky Diode



TO-220-3LD CASE 340AT



FFSP2065BDN = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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ABSOLUTE MAXIMUM RATINGS (T_C = 25° C unless otherwise noted)

Symbol	Parameter	Value	Unit	
V _{RRM}	Peak Repetitive Reverse Voltage	Peak Repetitive Reverse Voltage		
E _{AS}	Single Pulse Avalanche Energy (Note 1)		49*	mJ
١ _F	Continuous Rectified Forward Current @ T _C <	10*/20**	А	
I _{F, Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	650	А
		T _C = 150°C, 10 μs	570	А
I _{F,SM}	Non-Repetitive Forward Surge Current $T_{C} = 25^{\circ}C$	Half-Sine Pulse, t _p = 8.3 ms	42	A
Ptot	Power Dissipation	T _C = 25°C	60	W
		T _C = 150°C	10	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
	TO247 Mounting Torque, M3 Screw	60	Ncm	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. * Per Leg, ** Per Device 1. E_{AS} of 49 mJ is based on starting $T_J = 25^{\circ}$ C, L = 0.5 mH, $I_{AS} = 14$ A, V = 50 V.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	2.4*/1.3**	°C/W

* Per Leg, ** Per Device

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted (per leg))

Symbol	Parameter	Test Condition	Min	Тур	Мах	Unit
V _F	Forward Voltage	I _F = 10 A, T _C = 25°C	-	1.38	1.7	V
		$I_F = 10 \text{ A}, \text{ T}_C = 125^{\circ}\text{C}$	-	1.6	2.0	
		I _F = 10 A, T _C = 175°C	-	1.72	2.4	
I _R	Reverse Current	V_R = 650 V, T_C = 25°C	-	0.5	40	μΑ
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1	80	
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 175^{\circ}\text{C}$	-	2	160	
Q _C	Total Capacitive Charge	V = 400 V	-	25	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	421	-	pF
		V _R = 300 V, f = 100 kHz	-	40	-	1
		V _R = 600 V, f = 100 kHz	-	34	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Shipping
FFSP2065BDN-F085	FFSP2065BDN	TO-220-3LD (Pb-Free / Halogen Free)	50 Units / Tube

TYPICAL CHARACTERISTICS

 $(T_J = 25^{\circ}C \text{ unless otherwise noted (per leg)})$

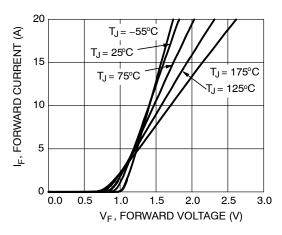


Figure 1. Forward Characteristics

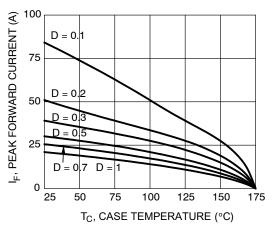


Figure 3. Current Derating

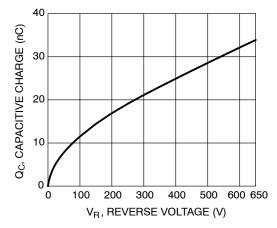


Figure 5. Capacitive Charge vs. Reverse Voltage

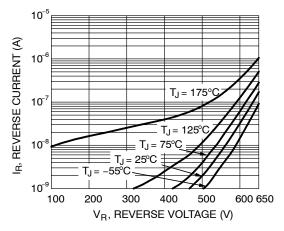
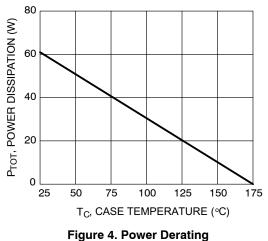


Figure 2. Reverse Characteristics



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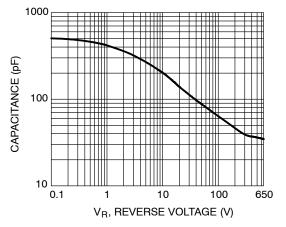


Figure 6. Capacitance vs. Reverse Voltage

TYPICAL CHARACTERISTICS

(T_J = 25°C unless otherwise noted)

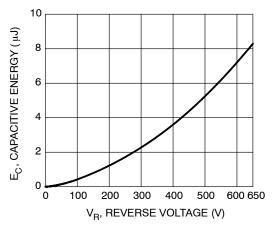


Figure 7. Capacitance Stored Energy

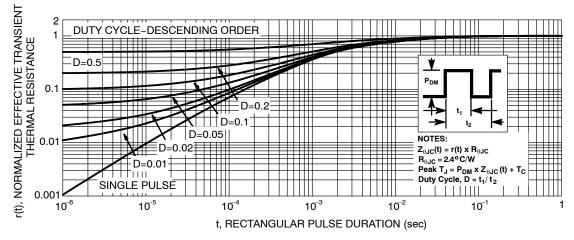
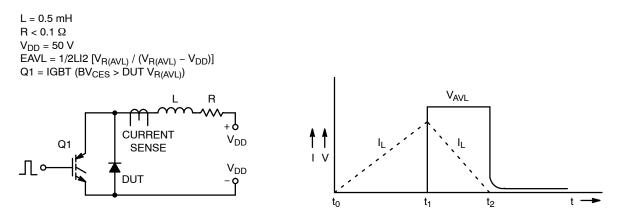


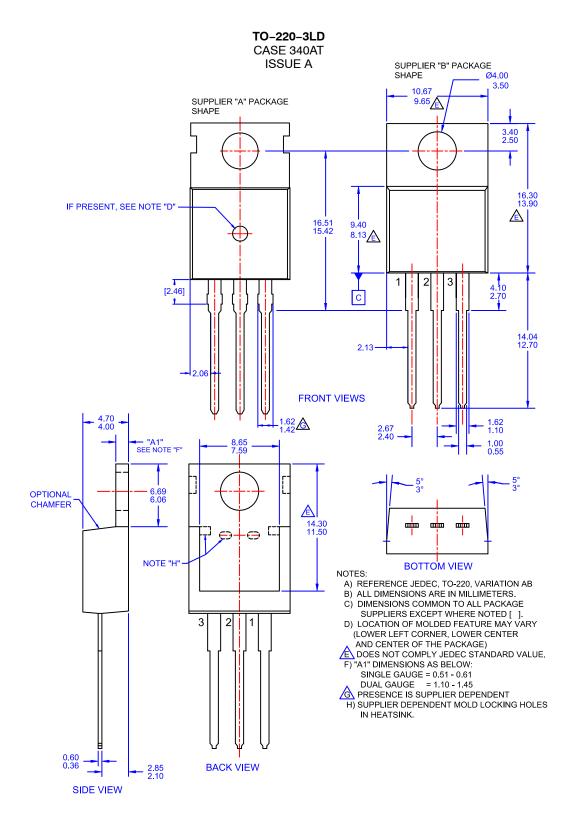
Figure 8. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS





PACKAGE DIMENSIONS



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